

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HUA CHAI	02/17/2014
RECEIVING PARTY DATA	
Name:	AMBIT MICROSYSTEMS (SHANGHAI) LTD.
Street Address:	NO.1925, NANLE ROAD, SONG JIANG EXPORT PROCESSING ZONE
City:	Shanghai
State/Country:	CHINA
Name:	HON HAI PRECISION INDUSTRY CO., LTD.
Street Address:	66, Chung Shan Road, Tu-Cheng Dist.
City:	New Taipei
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14185040
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ATTORNEY DOCKET NUMBER:	US47822
NAME OF SUBMITTER:	FRANK R. NIRANJAN

Signature:	/Frank R. Niranjana/
Date:	02/20/2014
Total Attachments: 2 source=US47822140219ASM#page1.tif source=US47822140219ASM#page2.tif	

ASSIGNMENT

In consideration of value received, the receipt and sufficiency of which are hereby acknowledged, the undersigned ASSIGNOR(S)

1. HUA CHAI, residing at Shanghai, China
2. _____, residing at _____
3. _____, residing at _____
4. _____, residing at _____
5. _____, residing at _____
6. _____, residing at _____
7. _____, residing at _____
8. _____, residing at _____

hereby sell(s), assign(s) and transfer(s) unto: **AMBIT MICROSYSTEMS (SHANGHAI) LTD.** having a principal place of business at **NO.1925, NANLE ROAD, SONG JIANG EXPORT PROCESSING ZONE, SHANGHAI 201613, P.R.C.** and **HON HAI PRECISION INDUSTRY CO., LTD.** having a principal place of business at **66, Chung Shan Road, Tu-Cheng Dist., New Taipei City, Taiwan, R.O.C.** hereafter designated "ASSIGNEE" the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100, in the invention and all patent applications including any and all divisions, continuations, substitutes, and reissues thereof, and all resulting patents, known as **BUILT-UP PLUG** for which the undersigned

[] previously executed --- Ser. No. _____ and filing date of _____
 [x] is executing concurrently herewith

an application for Letters Patent of United States of America

AND the undersigned hereby authorize(s) and request(s) the United States Commissioner of Patents and Trademarks to issue said Letters Patent to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree(s) that the attorneys of record in said application, if any, shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree(s) to testify and execute any papers for ASSIGNEE, its successors, assigns

1.	HUA CHAI	Feb 17, 2014
	HUA CHAI	Date
2.		Date
3.		Date
4.		Date
5.		Date
6.		Date
7.		Date
8.		Date